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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuto NISHIDA et al.

Attn: BOX PCT

Serial No. NEW

Docket No. 2001_1055A

Filed July 26, 2001

ELECTRONIC COMPONENT MOUNTING
METHOD AND APPARATUS
[Corresponding to PCT/JP00/00372
Filed January 26, 2000]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to initial examination of the above-identified New 371 National Stage application, kindly amend the application as follows:

IN THE CLAIMS:

3.(Amended) An electronic component mounting method as claimed in claim

1, wherein

A the insulating resin (6m) of the anisotropic conductive layer is an insulative thermosetting epoxy resin, and an amount of the inorganic filler mixed with this insulative thermosetting epoxy resin is 5 to 90 wt% of the insulative thermosetting epoxy resin.